



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Agarwal et al.

Patent No. 6,833,576

Issued: December 21, 2004

Confirmation No. 6254

For: METHODS FOR FORMING AND  
INTEGRATED CIRCUIT STRUCTURES  
CONTAINING RUTHENIUM AND  
TUNGSTEN CONTAINING LAYERS

Examiner: David Vu

Art Unit: 2818

Attorney Reference No. 6047-61466-01

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I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450 on the date shown below.

Attorney  
for Applicant(s)

Date Mailed January 24, 2005

TRANSMITTAL LETTER

The undersigned requests the following enclosed references be placed in the file for the patent referenced above:

- ☒ Ha et al., U.S. Patent 5,970,309
- ☒ Sun et al., U.S. Patent 6,010,931
- ☒ Please return the enclosed postcard to confirm that the items listed above have been received.

Respectfully submitted,

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cc: Docketing